

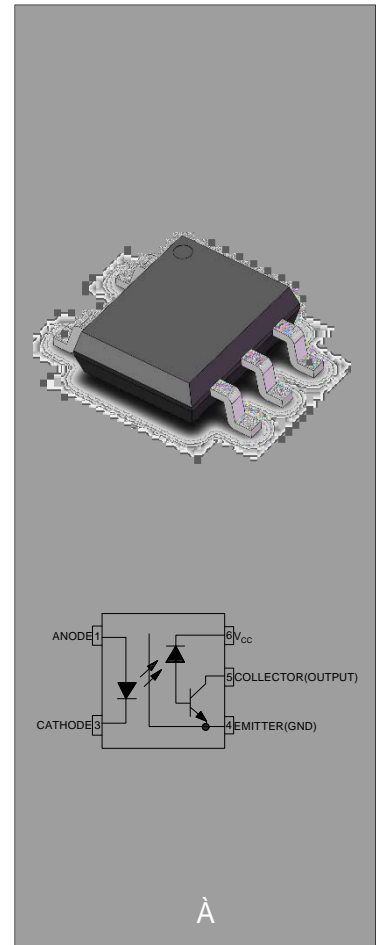


DESCRIPTION:

The products are 1MBd high-speed opto-couplers. The device is a small-outline coupler suitable for surface-mount assembly. It consists of a high-output-power infrared LED optically coupled to a high-speed photodiode-transistor chip. It is housed in the SOP5 package and guarantees a creepage distance of 5 mm, a clearance of 5 mm and an insulation thickness of 0.4 mm. Therefore, it meets the reinforced insulation class requirements of international safety standards. The products are widely used in programmable controllers, industrial inverters and switching power supplies.

MAIN FEATURES

High isolation 3750 VRMS
 High speed – 1MBd typical
 Operating temperature range -40°C to 110°C
 REACH & RoHS compliance
 HBM: H3A; MM: M4; CDM: C3
 CQC approved
 VDE approved
 UL approved



Truth Table

LED	Output
ON	L
OFF	H

ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Input	Forward Current	I _F	50	mA
	Peak Forward Current	I _{FP}	1 ⁷	A
	Reverse Voltage	V _R	6	V
	Input Power Dissipation	P _D	100	mW
Output	Supply Voltage	V _{CC}	35	V
	Output Voltage	V _O	20	V



Output Current

I_o



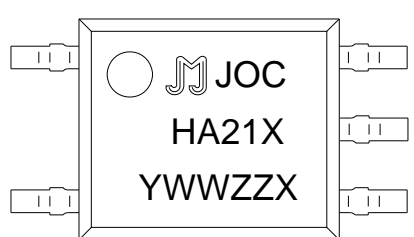
	Common Mode Transient Immunity at Logic High	CM _H	I _F =0mA, V _{CM} =400Vpp, R _L =4.1k	15	20	-	kV/μs
	Common Mode Transient Immunity at Logic Low	CM _L	I _F =16mA, V _{CM} =400Vpp, R _L =4.1k	-15	-20	-	kV/μs

ORDERING INFORMATION

J	OC	H	A	2	1	A	-M5	/
JieJie Microelectronics Co., Ltd.	Opto Coupler	High speed	Single OC	10V ∅V _{CC} 0.35V	1MBd high speed	A:CTR 0.20% B:20% ∅CTR 0.60% C:60% ∅CTR 0.120%	SOP5	None:T1 R:T2

Packing Quantity	
Option	Quantity
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MARKING



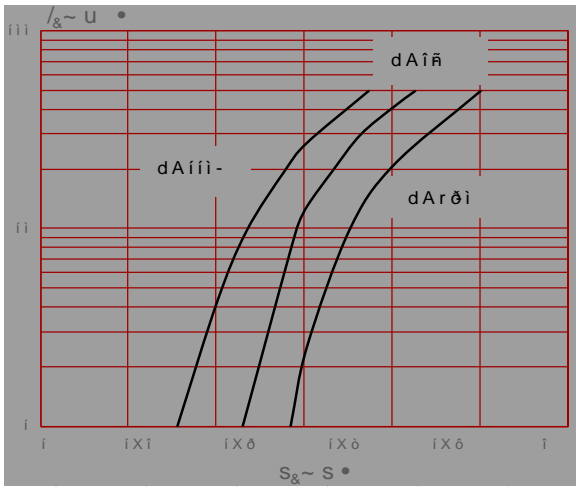
YWWZZX

LOT NO.

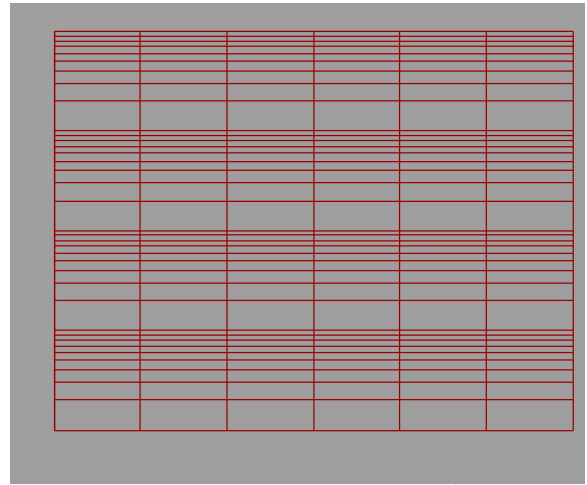


Characteristics Curves

Forward Current vs. Forward Voltage

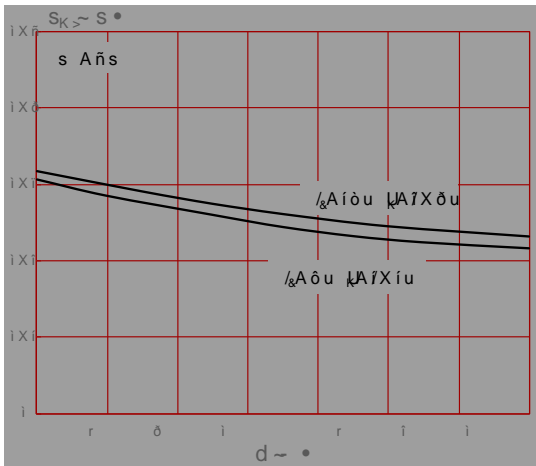


High Level Output Current vs. Ambient Temperature

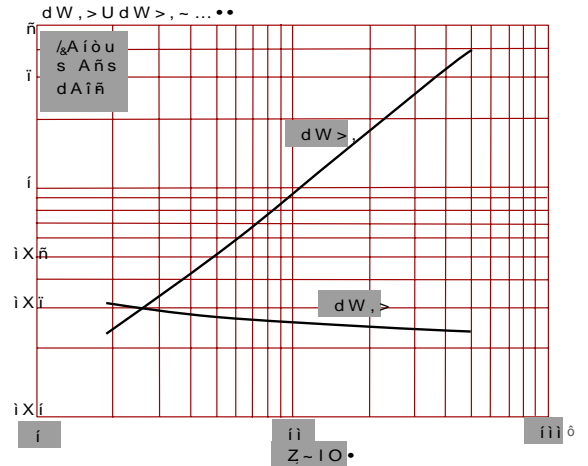




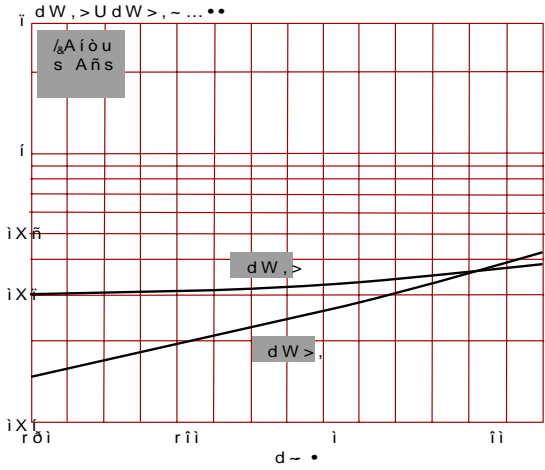
Low Level Output Voltage vs. Ambient Temperature



Propagation Delay vs. Load Resistance

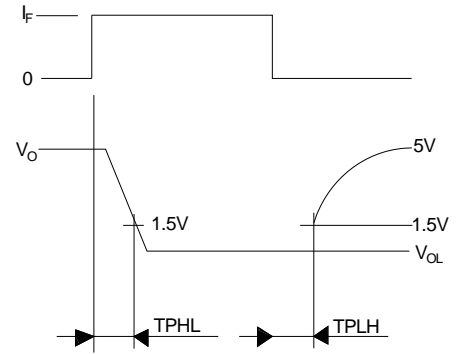
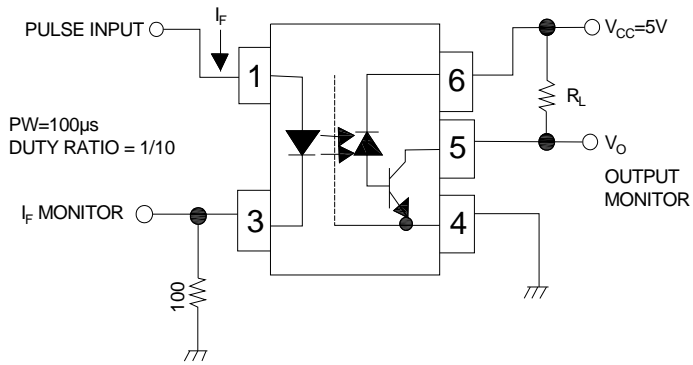


Propagation Delay vs. Ambient Temperature



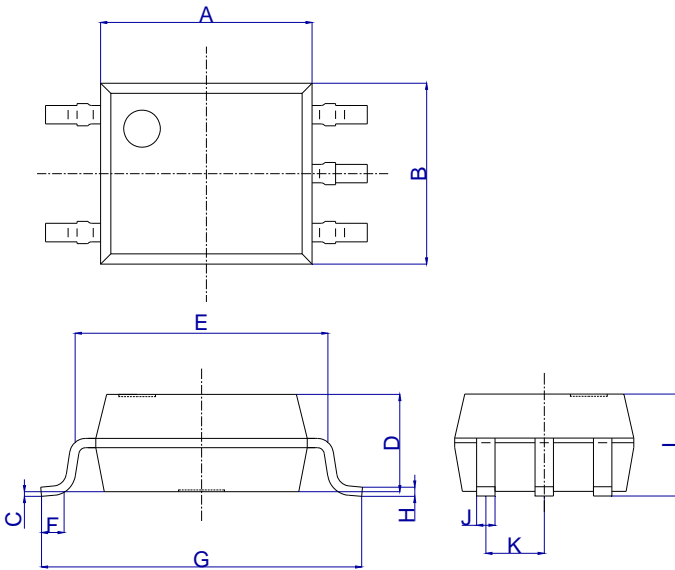


TEST CIRCUITS



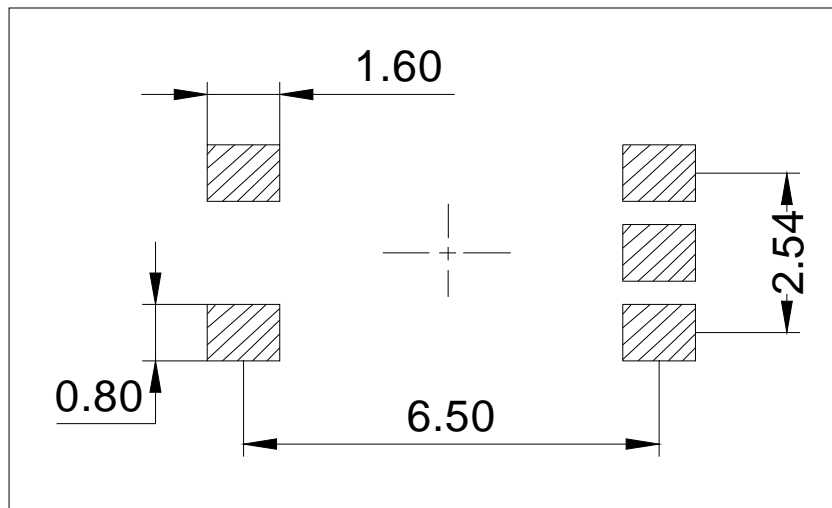


Package Dimension (Unit: mm)



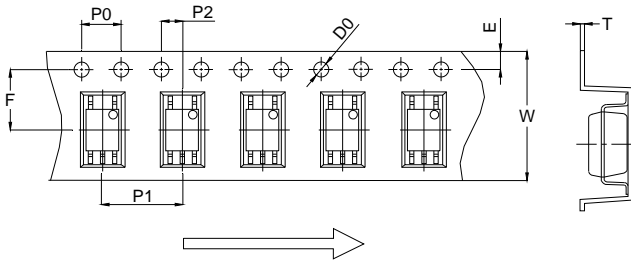
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.80	0.173		0.189
B	3.60		4.20	0.142		0.165
C	0.00		0.20	0.000		0.008
D	1.90		2.30	0.075		0.091
E	5.00		5.60	0.197		0.220
F	0.34		0.94	0.013		0.037
G	6.70		7.30	0.264		0.287
H	0.10		0.30	0.004		0.012
I	2.00		2.40	0.079		0.094
J	0.25		0.55	0.010		0.022
K	1.02		1.52	0.040		0.060

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

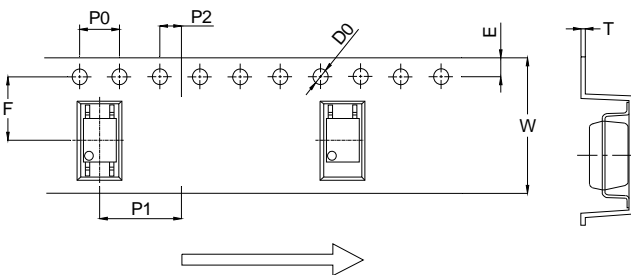




CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	4.40	4.50	4.60	0.173	0.177	0.181
T	0.25	0.30	0.35	0.010	0.012	0.014
W	11.90	12.00	12.30	0.469	0.472	0.484



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0						
P0						
P1						
P2						
E						
F						
T						
W						



REFLOW INFORMATION

Temperature 2 5

